## History Change

<table>
<thead>
<tr>
<th>Revision</th>
<th>Date</th>
<th>Description</th>
<th>Prepared By</th>
</tr>
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<tbody>
<tr>
<td>D01</td>
<td>2014/08/07</td>
<td>- Modified RF matching circuit and Net name.</td>
<td>Hsinwei Wang</td>
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<tr>
<td></td>
<td>2014/09/09</td>
<td>- Modified Assembling Item of PCM/BT_FUNC.</td>
<td></td>
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<tr>
<td>D02</td>
<td>2014/10/29</td>
<td>- Changed Project Code to GI</td>
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<tr>
<td></td>
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<td>- Updated RF matching.</td>
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<td></td>
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<td>- Modified Net names.</td>
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RD Approved

**Title Page**

**Date:** Wednesday, October 29, 2014  **Sheet** 1 of 2
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